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TABLE OF CONTENTS

Design of Fluorescent Spin-Crossover Nanoparticles for Thermometry Applications	2
<i>C. Quintero, G. Molnar, L. Salmon, A. Tokarev, C. Bergaud, A. Bousseksou</i>	
IOTA: Towards an Integrated On-chip Thermocouple Array	7
<i>J. Long, A. G. Klock, C. Zhou, S. O. Memik, M. Grayson</i>	
Thermal Modeling and Measurements of AlGaIn/GaN HEMTs including Thermal Boundary Resistance	13
<i>R. Sommet, G. Mouginot, R. Quere, Z. Ouarch, S. Heckmann, M. Camiade</i>	
Diagnostics of LED-based Streetlighting Luminaires by Means of Thermal Transient Method	18
<i>G. Marosy, Z. Kovacs, G. Molnar, A. Poppe</i>	
Crosstalk Compensation in Thermal Transient Measurements	24
<i>P. G. Szabo, V. Szekeley</i>	
Miniaturized Black Body Radiator for IR - Detector Calibration - Design and Development	28
<i>R. Schacht, C. Gerner, T. Nowak, D. May, B. Wunderle, B. Michel</i>	
Reliability Evaluation for Specifying Fatigue Mode in Power Device	33
<i>M. Kobayashi, Q. Yu</i>	
The New Approach to Modeling the Temperature Response in DBM Regime	39
<i>M. Kosikowski, Z. Suszynski</i>	
Method and Measurement Setup for Detection of the Shape of Optical Power Pulse in Active Thermography	45
<i>Z. Suszynski, M. Bednarek, M. Kosikowski</i>	
High Heat Flux Heat Sink with Adaptable Distribution of the Heat Extraction Capacity	49
<i>J. Barrau, J. Rosell, M. Ibanez, L. Tadrist</i>	
The Current-Voltage Characteristics of SiC Schottky Barrier Diodes with the Self-heating Included	53
<i>W. Janke, A. Hapka</i>	
Novel Method for the Assessment of Thermal Properties of High Power Thyristor Structure using Photoacoustic Technique with Composite Excitation Signal	56
<i>R. Duer, Z. Suszynski</i>	
Direct Electro-Thermal Simulation of Integrated Circuits using Standard CAD Tools	61
<i>J. C. Krencker, J. B. Kammerer, Y. Herve, L. Hebrard</i>	
The Photoacoustic Method of Determination of the Quantum Efficiency of Luminescence in Mn²⁺ Ions in Zn_{1-x-y}Be_xMn_ySe Crystals	65
<i>M. Malinski, L. Chrobak, J. Zakrzewski, K. Strzalkowski</i>	
Electro-thermal Simulations to Improve Heater Design in Preconcentration Membranes	71
<i>R. Ingles, J. Pallares, I. Garcia, A. M. Gue, J. L. Ramirez</i>	
Investigation of Tier-swapping to Improve the Thermal Profile of Memory-on-Logic 3DICs	74
<i>S. Melamed, T. Thorolfsson, A. Srinivasan, E. Cheng, P. Franzon, W. R. Davis</i>	
How Do We Know If A Structure Function Is Correct?	80
<i>A. Szalai, V. Szekeley</i>	
Power-Thermal Analysis of Multimedia Applications	84
<i>M. Marcu, C. Milos, D. Tudor</i>	
High-Power Test Device for Package Thermal Assessment and Validation of Thermal Measurement Techniques	90
<i>X. Jorda, X. Perpina, M. Vellvehi, F. Madrid, J. Altet</i>	
Impact of PCB via and Micro-via Structures on Component Thermal Performances	95
<i>E. Monier-Vinard, V. Bissuel, O. Daniel, M. Brizoux, A. Grivon, F. Pires, W. Mata</i>	
Thermal Characterization of SOI CMOS Micro Hot-Plate Gas Sensors	101
<i>I. Haneef, M. Burzo, S. Z. Ali, P. Komarov, F. Udrea, P. E. Raad</i>	
Compact Transient Thermal Model for 3D ICs with Liquid Cooling via Enhanced Heat Transfer Cavity Geometries	105
<i>A. Sridhar, A. Vincenzi, M. Ruggiero, T. Brunschweiler, D. Atienza</i>	
A Numerical Model of an Inter-strata Liquid Cooling Solution for a 3D IC Architecture	111
<i>D. Kearney</i>	
Hot Spot Detection in Integrated Circuits Laterally Accessing to their Substrate Using a Laser Beam	117
<i>X. Perpina, J. Altet, X. Jorda, M. Vellvehi</i>	
Improved Infrared Thermal Imaging of a CMOS MEMS Device	122
<i>R. H. Hopper, I. Haneef, S. Z. Ali, F. Udrea, C. H. Oxley</i>	

Thermal Impedance of AC LEDs	127
<i>A. Poppe, G. Farkas, T. Temesvolgyi, B. Katona, G. Molnar</i>	
The Problem of Infinitely Cascaded Thermoelectric Converters and their Optimization	133
<i>Y. C. Gerstenmaier, G. Wachutka</i>	
Electro-Thermal Characterization and Simulation of Integrated Multi Trenched XtremeMOS Power Devices	140
<i>J. Rhayem, B. Besbes, R. Bleic, S. Bychikhin, G. Haberfehrner, D. Pogany, B. Desoete, R. Gillon, A. Wieers, M. Tack</i>	
Experimental Validation of an Electro-Thermal Simulator for Metal Interconnections in Single-Layer PCB	144
<i>Y. Zhang, P. E. Bagnoli, A. Landi, P. Piaggi</i>	
Nonlinear Electro-Thermal OLED Model in SUNRED Field Simulator	149
<i>L. Pohl, E. Kollar, A. Poppe</i>	
Electro-thermal Coupling Analysis Methodology for RF Circuits	154
<i>D. Gomez, D. Mateo, J. Altet</i>	
Innovative Methodology to Extract Dynamic Compact Thermal Models: Application to Power Devices	160
<i>T. Azoui, P. Tounsi, J. M. Dorkel</i>	
Heat Transfer Enhancement in High-Power Heat Sinks using Active Reed Technology	165
<i>P. Hidalgo, F. Herrault, A. Glezer, M. Allen, S. Kaslusky, B. St. Rock</i>	
THERMINATOR: Modeling, Control and Management of Thermal Effects in Electronic Circuits of the Future	171
<i>A. Calimera, A. Macii, E. Macii, S. Rinaudo, M. Poncino</i>	
2D Thermal Propagation Analysis of Discrete Power Devices Based on an Innovative Distributed Model Technique and CAD Framework	177
<i>G. Bazzano, D. G. Cavallaro, G. Greco, A. Grimaldi, S. Rinaudo</i>	
Electro-thermal Co-simulation of ICs with Runtime Back-annotation Capability	183
<i>A. Timar, G. Bognar, A. Poppe, M. Rencz</i>	
Minimizing Temperature Sensitivity of Dual-Vt CMOS Circuits Using Simulated-Annealing on ISING-like Models	189
<i>M. Caldera, A. Calimera, A. Macii, E. Macii, M. Poncino</i>	
Experimental Characterization and Model Validation of Thermal Hot Spots in 3D Stacked ICs	195
<i>H. Oprins, V. Cherman, A. Srinivasan, M. Cupak, G. Van der Plas, P. Marchal, B. Vandeveld, E. Cheng</i>	
Thermo-sensitive Snapback Behavioral Model Intended for Electro-thermal Simulation of Power MOSFETs	200
<i>H. Dia, P. Tounsi, J. M. Dorkel</i>	
Major Achievements of the NANOPACK Project	204
<i>S. Demoustier, A. Ziaei</i>	
Performance of Thermal Interface Materials: Numerical Analysis	207
<i>J. V. Goicochea, W. Escher, X. Tang, B. Michel</i>	
Influences of Technological Processing and Surface Finishes on Thermal Behaviour of Thermal Interface Materials	213
<i>M. Abo Ras, B. Wunderle, D. May, H. Oppermann, R. Schacht, B. Michel</i>	
Transient TIM Measurements for In-situ Thermal Characterization of Microprocessors	219
<i>G. Farkas, C. Barna</i>	
Re-design and Validation of the 'STATIM' TIM Tester	224
<i>V. Szekeley, A. Vass-Varnai, E. Kollar</i>	
In-situ Characterization of Thermal Interface Materials	228
<i>A. Vass-Varnai, Z. Sarkany, M. Rencz</i>	
Simultaneous Topographic and Thermal Imaging of Silicon Nanowires using a New SThM Probe	234
<i>E. Puyoo, S. Grauby, J. M. Rampoux, W. Claeys, E. Rowiere, S. Dilhaire</i>	
Thermal Interfaces based on Vertically Aligned Carbon Nanotubes: An Analysis of the Different Contributions to the Overall Thermal Resistance	240
<i>H. Le Khanh, L. Divay, P. Le Barny, E. Leveugle, E. Chastaing, S. Demoustier, A. Ziaei, S. Volz, J. Bai</i>	
Thermal Interface Materials based on Carbon Nanotubes and their Thermal Characterization	244
<i>M. Kasimir, K. Gharagozloo-Hubmann, S. Trotsenko, G. J. F. Czempiel, V. Datsyuk, S. Reich</i>	
Effect of Phonon Confinement on Heat Dissipation in Ridges	250
<i>P. O. Chapuis, M. Prunmila, A. Shchepetov, L. Schneider, S. Laakso, J. Ahopelto, C. M. Sotomayor Torres</i>	
A Device for the Measurement of the Thermal Properties of Small (μL) Volumes	256
<i>J. J. Atherton, M. C. Rosanond, S. Johnstone, D. A. Zeze</i>	
Two-Phase Flow Boiling of R134a in a Multi-Microchannel Heat Sink for Microprocessor Cooling	260
<i>Y. Madhour, J. Olivier, E. Costa-Patry, S. Paredes, B. Michel, J. R. Thome</i>	

Pin-Shape Assessment for Interlayer-Cooled Chip Stacks with Periodic Boundary Condition Modeling	266
<i>G. Toral, R. Bender, Y. Leblebici, T. Brunschweiler</i>	
Hot-Spot Self-Cooling Effects on Two-Phase Flow of R245fa in 85μm-wide Multi-Microchannels	276
<i>E. Costa-Patry, J. Olivier, S. Paredes, J. R. Thome</i>	
Development of Vertical Superlattices in Silicon for On-Chip Thermal Management	282
<i>J. Parasuraman, M. Bardoux, P. Basset, D. Angelescu, P. Chantrenne, T. Bourouina</i>	
Mathematical and Computing Modeling of Temperature Fields in Electronic Modules	285
<i>P. I. Kandalov, A. G. Madera</i>	
Author Index	